		Doc. No.	X-A0162-59	Page No.	1/9
XKB Connectivity	XKB Connectivity	Date Issued	2020-04-06	Prepared by	Josephine
	·	Date revised	2020-11-23	checked by	Jay
Product Specification		Rev. No.	01	Approved by	Mei Chen

1. SCOPE(适用范围)

This specification covers the performance, tests and quality requirements for the 2.50mm series wire to board connector. (XKB Connectivity 本规范涵盖了盖2.50mm系列线对板连接器性能、测试和质量要求)

2. PRODUCT DESCRIPTION(产品描述)

DESCRIPTION(描述)	Part Number(料号)
Housing 胶壳	X2514HI-XXL-0-0A

3. APPLICABLE DOCUMENT (适用文件)

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence. (XKB Connectivity 下列文件构成本规范的一部分,在此规定的范围内。本规范要求与产品图纸有冲突时,以产品图纸为准。如果本规范的要求与参考文件发生冲突,应以本规范为准。)

4. REQUIREMENTS (要求)

4.1. Design and Structure (设计和结构)

Product shall be of the design, structure and physical dimensions specified on the applicable product drawing. (XKB Connectivity 产品的设计、结构和物理尺寸参考所适用的产品图纸)

4.2. Materials/Finish (材料/表面处理)

Specification 规格内容	Materials 材质	Disposal of Surface 表面处理
Terminal 端子		Tin Plated: Over 70μ. Nickel: Over 30μ″
Housing胶壳	PA66 / UL94V	UL 94V-2/UL94V-0

Doc. No. 2/9 X-A0162-59 Page No. **XKB** Connectivity Date Issued 2020-04-06 Prepared by Josephine Date revised 2020-11-23 checked by Jay **Product Specification** Rev. No. 01 Mei Chen Approved by

Title: 2.50mm Pitch X2514 Series Connector

Wafe	Base	UL 94V-2/UL94V-0	
针座	PIN	Over Tin 70µ″ Plated ; Over 30µ″ Nickel	

Please Refer to the Project drawing for the above Specification. (上述参数请以工程图为准)

4.3. Ratings (额定功率)

XKB Connectivity Item(项目)	Standard (标 准)		
Rated Voltage (Maximum) 额定电压	250V	1.0/2.0	
Rated Current (Maximum) 额定电流	3A	AC/DC	
Ambient temperature Range 使用温度范围	-40°C ∼+110°C		
7 thiorent temperature Range (2717)m/275	From -40 to +110 degree centigrade		
Applicable wire insulation O.D 适用线径	AWG 22#~24# Insulation O.D.		
Applicable wife insulation O.D Emiszie	mm(l	Max.)	
NOTE备注: Including terminal temperature rise 升温时含端子			

5. TEST STANDARD (测试条件)

5.1 Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows (除另有说明外, 用以进行测量和测试的标准 环境条件范围如下)

Ambient temperature(环境温度): 5℃ to 35℃ Normal humidity (正常湿度): 45% to 85%

Air pressure (气压): 86Kpa to 106Kpa

5.2 However if doubt arises on the decision based on the measured Values under the above-mentioned Conditions. The following conditions shall be employed:

(但是在对判定产生疑问时,按下述状态实施)

Temperature (温度): 20±2℃

Relative humidity (相对湿度): 65±5%

Air pressure (气压): 86Kpa to 106Kpa

8. PERFORMANCE AND TEST DESCRIPTION (性能和测试类型)

8.1 APPEARANCE (外观)

ITEM	DESCRIPTION(类型)	TEST CONDITION(测试条件)	REQUIREMENT(要求)

			X-A0162-59	Page No.	3/9
XKI3	XKB Connectivity	Date Issued	2020-04-06	Prepared by	Josephine
	·		2020-11-23	checked by	Jay
Product Specification		Rev. No.	01	Approved by	Mei Chen
Citle * 2 50mm Ditch V2514 Sories Connector					

1	Appearance (外观)	Visual.(目视)	Should not have any flaw Scratch discoloration and crushed(无任何裂痕、刮伤 、污染和变形)
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8.2 ELECTRICAL (电气)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT (要求)
1	contact resistance (接触阻抗)	Based upon EIA-364-06A. Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (公母配合, 开放电压 20mV 以下, 电流 10	Initial(初始): 10 milliohms Max. After Test(测试后): 20 milliohms Max.
2	Insulation Resistance (绝缘阻抗)	Based upon EIA-364-21B/MIL-STD-202 Method 302 Cond. B Mate connectors, apply 500V DC between adjacent terminal or ground. (公母配合, 在相邻端子, 端子与地片之间, 使用500V 的直流电,检测连接器)	$1000~ ext{M}\Omega$ min.
3	Dielectric strength (耐电压)	Based upon EIA-364-20A/MIL-STD-202 Method 301 Mate connectors, apply 1000V AC for 1 minute between adjacent terminal or ground. (公母配合, 在相邻端子, 端子与地片之间, 使用1000V 的交流电 1 分锺, 检测连接器)	There shall be no breakdown. (无击穿、闪烁现象)
4	Contact resistance on crimped portion(铆线后端子接触阻抗)	Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA. (铆线后之端子, 开放电压 20mV 以下, 电流 10mA检测连接器)	10 milliohms

8.3 MECHANICAL (机械)

ITEM	DESCRIPTION (类型)	TEST CONDITION (测试条件)	REQUIREMENT(要求)
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		Doc. No.	X-A0162-59	Page No.	4/9
XKB	XKB Connectivity	Date Issued	2020-04-06	Prepared by	Josephine
	·	Date revised	2020-11-23	checked by	
Product Specification		Rev. No.	01	Approved by	Mei Chen
TP:41					

1	Insertion & Retention Force (插拔力)	Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute. (以每分锺 25.4±3mm 的速率插入和拔出)	Refer to paragraph 6 参照第 10 项			
2	Terminal/ Housing Retention Force (端子保持力)	Apply axial pu rce at the speed rate of 25.4±3mm/mmute on the terminal assembled in the housing. (以每分 25.4±3mm 的速率,将端子从 Housing 内轴向拔出的力量.)	24.5N {2	:.5kgf}l	Min.	
3	Terminal Insertion Force (端子插入力)	Insert the crimped terminal into the housing. (铆线后之端子插入Housing 所需最大力量)	14.7N {1.5kgf} Max.			
4	PIN Retention Force (PIN针保持力)	Apply axial push force at the speed rate of 25.4±3mm/minute. (以每分 25.4±3mm 的速率,将 PIN 针从Wafer 内轴向拔出的力量)	13.7N {1.4kgf} min.			
		Fix the crimped terminal, apply axial	AWG	#20	#22	#24
	Tensile strength	pull out force on the wire. (Do not crimp insulation part). (固定铆线后的端子,使电线与端子分离时	Spec. kgf. Min.	6.0	4.0	2.0
5	(Crimped connections)(端子压 着强度)	所需的: Contact Wire Pulling load	spec	e sizes ificatio	unspec in this on defi n clien	s ne
6	Repeated Insertion/ Withdrawal (重复插拔)	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute. (以每分锺不超过 10 次的速率,将公母插拔30 次.)	Resistan 0 m			

		Doc. No.	X-A0162-59	Page No.	5/9
XKB	XKB Connectivity	Date Issued	2020-04-06	Prepared by	Josephine
	·	Date revised	2020-11-23	checked by	Jay
Pr	oduct Specification	Rev. No.	01	Approved by	Mei Chen
Title: 2 50mm Ditch Y2514 Series Connector					

7	Vibration (耐振动性)	Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A Amplitude(振幅): 1.5mm P-P Sweep time(频率): 10~55~10 HZ in 1 minute Duration(持续时间): 2 hours in each X.Y.Z axials.(每轴向 2 小时)	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max. Discontinuity瞬断:1 micro- second Max.
8	Shock (耐冲击性)	Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A Pulse width(冲击时间): 11 msec., Waveform(波形): half sine, 490m/s2{50G}, 3 strokes in each X.Y.Z. axes. (加速度最大50G,沿3个互相垂直达的方向)	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max. Discontinuity瞬断:1 micro- second Max.

8.4 ENVIRONMENTAL (环境)

ITEM	DESCRIPTION (类型)	TEST CONDITION(测试条件)	REQUIREMENT (要求)
1	Temperature Rise(温升测试)	Carrying rated current load. (UL 1977)(公母对插后, 在通过额定电流下, 所测定的温度)	30 ℃ Max.
2	Heat Resistance (耐热性)	Based upon MIL-STD-202 Method 108A Cond.A 85±2°C,96 hours.	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max.
3	Cold Resistance (耐寒性)	Based upon EIA-364-105 -25±5℃,96 hours.	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max.

		Doc. No.	X-A0162-59	Page No.	6/9
XKB Connectivity	XKB Connectivity	Date Issued	2020-04-06	Prepared by	Josephine
	v	Date revised	2020-11-23	checked by	Jay
Pr	oduct Specification	Rev. No.	01	Approved by	Mei Chen
Title: 2.50mm Ditch V2514 Series Connector					

4	Humidity (耐湿性)	Based upon EIA-364-31A/MIL-STD- 202 Method 103B Cond.B Temperature(温度): 40±2℃ Relative Humidity(湿度): 90~95% Duration(持续时间): 96 hours	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max. Insulation Resistance 绝缘阻抗: 1000 ΜΩ min.
5	Temperature Cycling (温度变化)	Based upon EIA-364-32B 5 cycles of: a) -55℃ 30 minutes. b) +85℃ 30 minutes. (从-55℃持续 30 分锺升至+85℃持续 30 分锺,循环 5 次)	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max.
6	Salt Spray (盐水喷雾)	Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond.B 24±1 hours exposure to a salt spray from the 5±1% solution at 35±2℃. (在温度 35±2℃, 盐水浓度 5±1%下, 盐水喷雾24±1 小时) 注:此项测试只针对先冲后镀端	Appearance外观: No Damage无异状 Contact Resistance接触阻抗:20 milliohms Max.
7	Solder-ability (焊锡附着性)	Based upon EIA-364-52 Soldering Time焊接时间: 3±0.5second. Solder Temperature焊接温度: 245±5℃.	Immersed area must show no voids, pin holes. 浸渍面积需95%以上
8	Solder- Resistance (焊锡耐热性)	Based upon EIA-364-56A Soldering time焊接时间:3~5 sec Solder Temperature焊接温度:250±5℃.	Appearance外观: No Damage无异状

	XKB Connectivity		X-A0162-59	Page No.	7/9
XKB Connectivity			2020-04-06	Prepared by	Josephine
	-	Date revised	2020-11-23	checked by	Jay
Product Specification		Rev. No.	01	Approved by	Mei Chen
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9. PACKAGING 包装

Please refer to the packing drawing. 请参考产品包装图纸

10. INSERTION/WITHDRAWAL FORCE 综合插入力及拔出力:

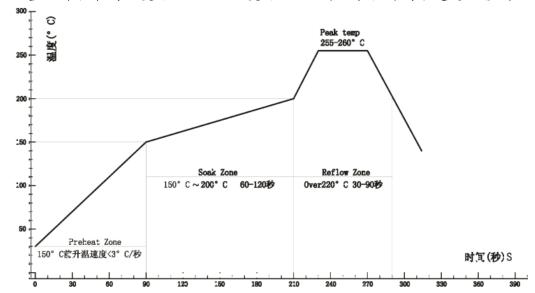
参考附件

11. SOLDERING 焊接:

- 11.1. Wave soldering (波峰焊): DIP Suggestions solder temperature at 260°C(500°F) max.5 seconds . DIP型推荐焊接焊锡温度为260°C (500°F) 最多5秒
- 11.2. Hand soldering (手焊): Use a soldering iron of 30 watts controlled at 350℃ approximately 5 seconds. while applying solder. 使用30W烙铁控制温度在350℃,焊接时长约5秒

		Doc. No.	X-A0162-59	Page No.	8/9
XKB Connectivity	XKB Connectivity	Date Issued	2020-04-06	Prepared by	Josephine
	·	Date revised	2020-11-23	checked by	Jay
Pr	oduct Specification	Rev. No.	01	Approved by	Mei Chen
Title : 2.50mm Ditch V2544 Carine Connector					

11.3. Reflow soldering profile (回炉焊):When the maximum temperature of the reflow furnace is 260 °C and the temperature is 260 °C. 10 seconds MAX. (reference) SMT型回焊炉最高温度为260℃,温度为260℃时,最长时间不超过10秒(如图)



Rev.	Description	Date revised	Created/ Revised by
01	New Release	2021/05/20	Josephine Lin